

# EMI Ferrite Bead



## BBHV Series



### Overview

EMI ferrite beads are made of ferrite material, which can block high-frequency noise while allowing required signals to pass through, providing high impedance and noise attenuation to improve signal integrity/efficiency and reduce power loss.

### Benefits

1. Compliance with EMI regulations.
2. Reduced power loss and improved system efficiency
3. Operating temperature range: -55 ~ +125°C
4. Improved signal integrity

### Applications

1. Wearable Devices
2. Industrial
3. Communications
4. Consumer Electronics

### Product Information

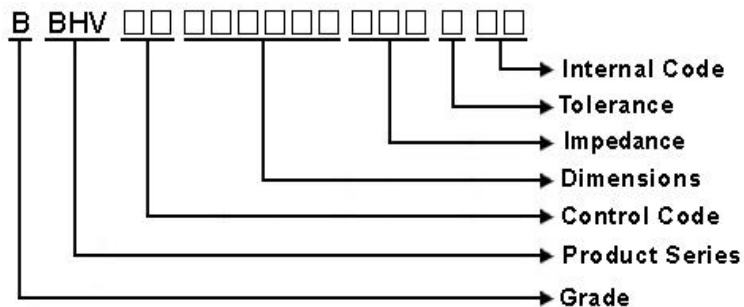
Series	Size Code (JIS/EIA)	Impedance ( $\Omega$ )
BBHV	1608/0603	10 ~ 600



## BBHV00160808 Series Specification

**1 Scope:** This specification applies to Multilayer Ferrite Chip Power Beads

**2 Part Numbering:**



**3 Rating:**

Operating Temperature: - 55 °C ~ 125 °C(Including self - temperature rise)

Storage Temperature: - 55 °C ~ 125 °C(after PCB)

- 5 °C~ 40 °C, Humidity 40 %~ 70 %(before PCB)

**4 Marking:**

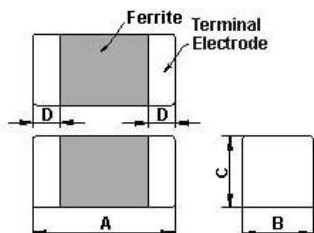
No Marking

**5 Standard Testing Condition**

	Unless otherwise specified	In case of doubt
Temperature	Ordinary Temperature(15 to 35°C)	20 to 30°C
Humidity	Ordinary Humidity(25 to 85% RH)	50 to 80 %RH

## BBHV00160808 Series Specification

### 6 Configuration and Dimensions:



Dimensions in mm

TYPE	160808
A	1.6±0.15
B	0.8±0.15
C	0.8±0.15
D	0.3±0.20

Net Weight (grms)

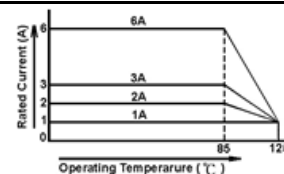
Size Code	Net Weight (grms)
160808	0.00576

### 7 Electrical Characteristics:

Part No.	Impedance (Ω)	Test Freq.	RDC (Ω)Max.	Rated Current (mA)Max.
BBHV00160808100Y00	10	100 MHz, 200 mV	0.01	6000
BBHV00160808300Y00	30	100 MHz, 200 mV	0.015	4000
BBHV00160808600Y00	60	100 MHz, 200 mV	0.03	3000
BBHV00160808121Y00	120	100 MHz, 200 mV	0.04	3000
BBHV00160808201Y00	200	100 MHz, 200 mV	0.05	2500
BBHV00160808221Y00	220	100 MHz, 200 mV	0.08	2000
BBHV00160808301Y00	300	100 MHz, 200 mV	0.08	2000
BBHV00160808331Y00	330	100 MHz, 200 mV	0.08	2000
BBHV00160808471Y00	470	100 MHz, 200 mV	0.1	2000
BBHV00160808601Y00	600	100 MHz, 200 mV	0.1	2000

**NOTE:** tolerance Y=±25%

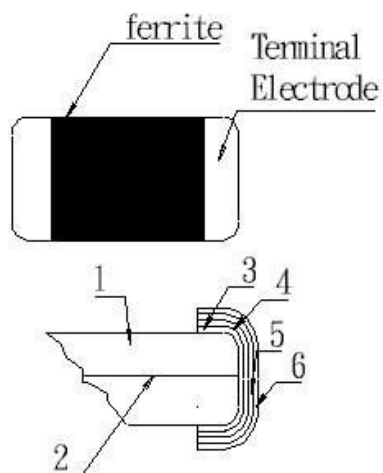
- Operating temperature range - 5 5 °C ~ 1 2 5 °C(Including self - temperature rise)
- Rate Current : Applied the current to coils, the temperature rise shall not be more than 30°C
- Impedance Test OSC @200mV



## BBHV00160808 Series Specification

### 8 BBHV00160808 Series

#### 8.1 Construction:



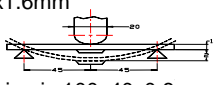
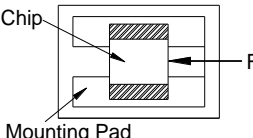
#### 8.2 Material List:

No	Part	Material
1	Ferrite Substance	NiO-CuO-ZnO-Ferrite
2	Silver electrode	Ag
3	Silver electrode	Ag
4	Cu plating	Cu
5	Ni plating	Ni
6	Sn plating	Sn

## BBHV00160808 Series Specification

### 9 Reliability Of Multilayer Ferrite Chip Power Beads

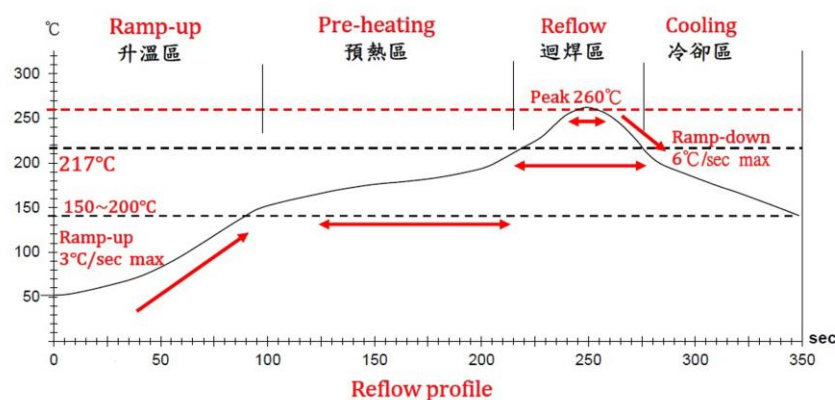
#### 1-1.Mechanical Performance

No	Item	Specification	Test Method
1-1-1	Flexure Strength	The forces applied on the right conditions must not damage the terminal electrode and the ferrite	Test device shall be soldered on the substrate Substrate Dimension: 100x40x1.6mm Deflection: 2.0mm Keeping Time: 30sec *For 100505, substrate dimension is 100x40x0.8mm 
1-1-2	Vibration		Test device shall be soldered on the substrate Oscillation Frequency: 10 to 55 to 10Hz for 1min Amplitude: 1.5mm Time: 2hrs for each axis (X, Y & Z), total 6hrs
1-1-3	Resistance to Soldering Heat	Appearance: No damage More than 75% of the terminal electrode should be covered with solder. Impedance : within $\pm 30\%$ of initial value	Pre-heating: 150°C, 1min Solder Composition: Sn/Ag3.0/Cu0.5(Pb-Free) Solder Temperature: 260 $\pm 5$ °C Immersion Time: 10 $\pm 1$ sec
1-1-4	Solder ability	The electrodes shall be at least 95% covered with new solder coating	Pre-heating: 150°C, 1min Solder Composition: Sn/Ag3.0/Cu0.5(Pb-Free) Solder Temperature: 245 $\pm 5$ °C (Pb-Free) Immersion Time: 4 $\pm 1$ sec
1-1-5	Terminal Strength Test	No split termination  Chip Mounting Pad	Test device shall be soldered on the substrate, then apply a force in the direction of the arrow. Force : 5N Keeping Time: 10 $\pm 1$ sec

#### 1-2.Environmental Performance

1.2 Environmental Performance					
No	Item	Specification	Test Method		
1-2-1	Temperature Cycle	Appearance: No damage Impedance: within±30% of initial value	One cycle:		
			Step	Temperature (°C)	Time (min)
			1	-55±3	30
			2	25±2	3
			3	125±3	30
			4	25±2	3
			Total: 100cycles		
			Measured after exposure in the room condition for 24hrs		
1-2-2	Humidity Resistance		Temperature: 40±2℃ Relative Humidity: 90 ~ 95% / Time: 1000hrs Measured after exposure in the room condition for 24hrs		
1-2-3	High Temperature Resistance		Temperature: 125±3℃ / Relative Humidity: 0% Applied Current: Rated Current /Time: 1000hrs Measured after exposure in the room condition for 24hrs		
1-2-4	Low Temperature Resistance		Temperature: -55±3℃ Relative Humidity: 0% / Time: 1000hrs Measured after exposure in the room condition for 24hrs		

## BBHV00160808 Series Specification



Lead-Free(LF)標準溫度分析範圍

Refer to J-STD-020C

管制項目 Item.	升温區 Ramp-up	預熱區 Pre-heating	迴焊區 Reflow	Peak Temp	冷卻區 Cooling
溫度範圍 Temp.scope	R.T ~ 150°C	150°C ~ 200°C	Above 217°C	260±5°C	Peak Temp.~150°C
標準時間 Time spec.	—	60 ~ 180 sec	60 ~ 150 sec	20 ~ 40 sec	—
實際時間 Time result	—	75 ~ 100 sec	90 ~ 120 sec	20 ~ 35 sec	—

NOTE :

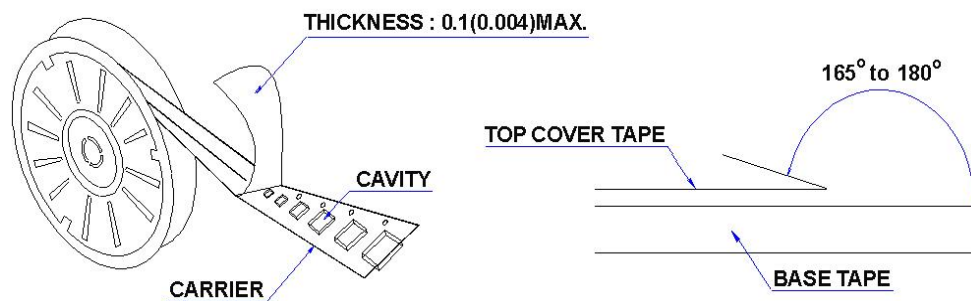
1. Re-flow possible times : within 2 times
2. Nitrogen adopted is recommended while in re-flow
3. Products can only be soldered with reflow

## BBHV00160808 Series Specification

### 11 Packaging:

#### 11.1 Packaging -Cover Tape

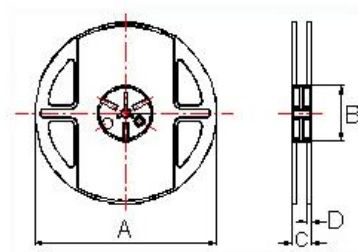
The force for tearing off cover tape is 10 to 100 grams in the arrow direction.



#### 11.2 Packaging Quantity

TYPE	PCS/REEL
160808	4000

#### 11.3 Reel Dimensions



Dimensions in mm

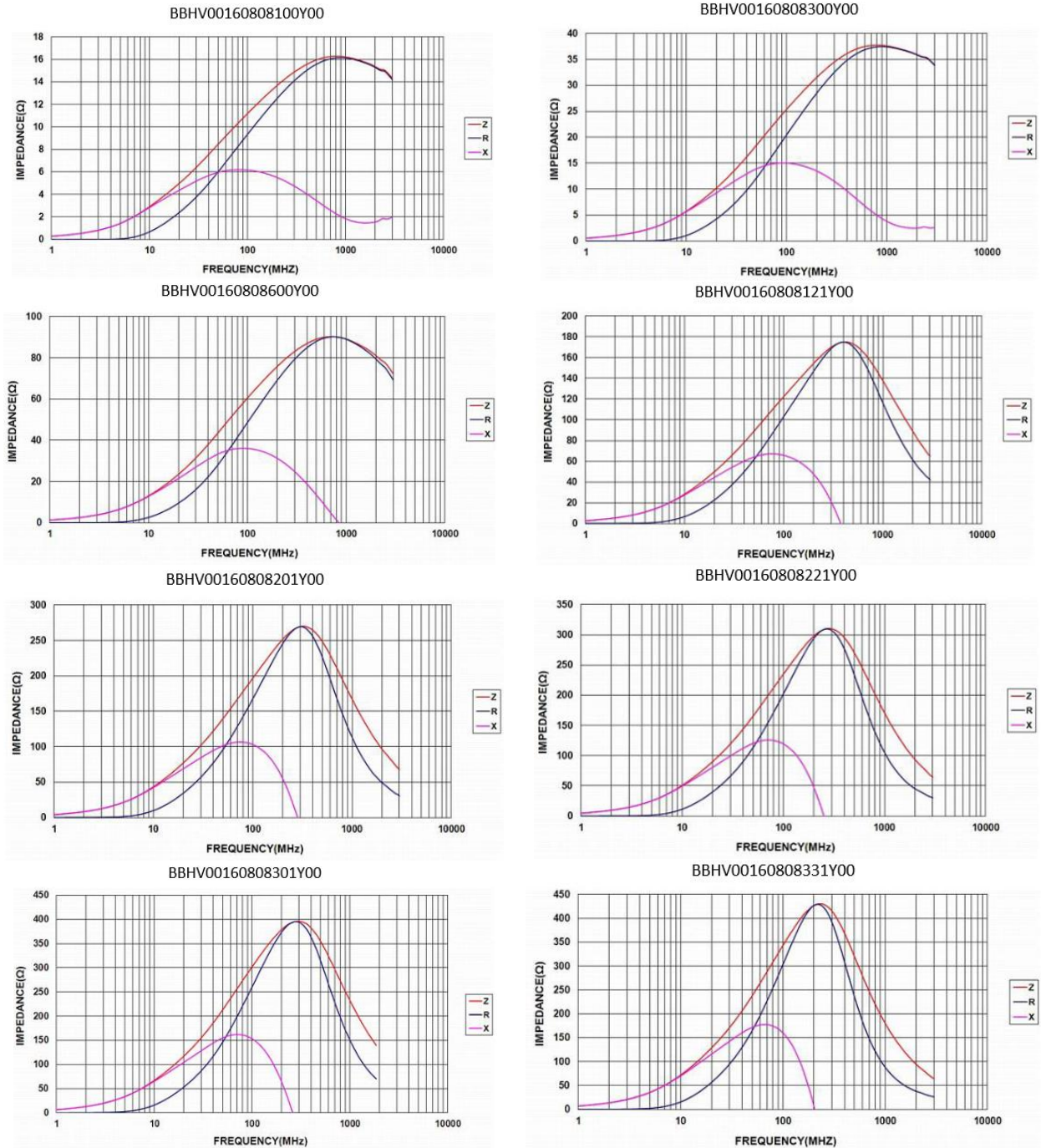
TYPE	A	B	C	D
160808	178	60	12	1.5





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### 14 Graph:



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### 14 Graph:

